

EV Group advances leadership in optical lithography with next-generation EVG150 resist processing platform – November 7, 2022



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Top Stories

What the CHIPS and Science Act could mean for domestic semiconductor manufacturing innovation

It's important for semiconductor companies to utilize the CHIPS Act funding as effectively as possible. One way to do this is by switching to a chiplet-based design flow. <u>More>></u>

Samsung Electronics begins mass production of 8th gen vertical NAND with industry's highest bit density

Samsung Electronics Co., Ltd., as promised at Flash Memory Summit 2022 and

Samsung Memory Tech Day 2022, announced today that it has begun mass producing a 1-terabit (Tb) triple-level cell (TLC) eighth-generation Vertical NAND (V-NAND) with the industry's highest bit density. <u>More>></u>



Join the Global Semiconductor and Electronics Forum (GSEF) 2022

Tap into 5G, 6G and the next level of advanced communications with GSEF 2022 on 27-28 October in San Francisco! The forum will discuss the vital connections between processes, tools and techniques to manage change. Register now to update your knowledge and create new strategies enabling you to enact change. Learn more.

Tech News

EV Group advances leadership in optical lithography with next-generation EVG150 resist processing platform

Redesigned 200mm platform increases module capacity for higher throughput, improves architecture for reduced tool footprint all while maintaining industry-leading capabilities of previous-generation platform. <u>More>></u>

FEATURED PRODUCT

Control Wafer Thickness Variation

Marposs sensors improve production and assure high-quality processes such as ingot slicing, wafer lapping and wafer back grinding by monitoring thickness, force, torque, vibration, acceleration, true power, coolant flow and acoustics. These sensors work inside a machine and immediately detect events or changes in the machine environment. Learn more.



You're Invited — Assured Microelectronics Summit! DSI's Assured Microelectronics Summit, taking place November 2-3 in Washington, DC, will convene DoD, US government, industry, and academia to discuss the technologies and policies needed to enhance microelectronics capabilities to support increased supply chain resilience and national security efforts. Active-duty military and government attend FREE! **Register today**.

Featured Video



Marposs: Bringing New Solutions to Inspection, Measurement and Monitoring

Frank Powell, who is in charge of business development in semiconductor for Marposs, and Patrice Belin, product manager for STIL, a division of Marposs, talk to Semiconductor Digest editor Pete Singer about the company, its products and their applications. Marposs Company provides precision metrology equipment in the form of probes, in-process gauges and non-contact sensors for process control and monitoring. The STIL group adds chromatic confocal and interferometry technology to the line-up. Applications include ingot slicing, lapping/polishing/CMP, back grinding and machine monitoring. Chromatic confocal tech is used to produce high-accuracy bump measurements.



Business News

Global silicon wafer shipments projected to set new record in 2022, SEMI reports

Global silicon wafer shipments are projected to increase 4.8% year-over-year in 2022 to a record high of nearly 14,700 millions of square inches (MSI), SEMI reported today in its annual silicon shipment forecast for the semiconductor industry. <u>More>></u>

SEMICON Europa 2022 keynotes to highlight chip industry growth opportunities and advanced technologies

Registration for the event, co-located with electronica, is now open. More>>

Semiconductor Climate Consortium representatives to present during 2022 United Nations Climate Change Conference

SEMI today announced that members of the new Semiconductor Climate Consortium (SCC) will discuss key aspects of the group's vision, goals and membership at two sessions during COP27 in Sharm EI-Sheik, Egypt. <u>More>></u>



Webinars and Technology Papers

Faster Processes and Tighter Control with a High-Speed Liquid Flow Control Designed for CVD and ALD Applications View on Demand

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How Dynamic Force Measurement is Driving the Semiconductor Ecosystem Ahead View on Demand

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Optimize Wafer Quality and Yield with Real-time Data During the CMP Process <u>View on Demand</u>

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Should I Expect? View Paper

Using Piezoelectric Sensors to Measure Dynamic Force in Semiconductor Applications <u>View Paper</u>

Not All Greenhouse Gases Are the Same - Biggest Benefits Come From Ranking Greenhouse Gas Reduction Impact <u>View Paper</u>

MSP — PID Tuning Liquid Flow Controllers (LFCs) for Fast Response & Stabilization Time <u>View Paper</u>

> When OES is in the Dark: New Metrology Solutions for Advanced ALD, Chamber Management and Sub FAB Safety and Sustainability Applications View on Demand



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